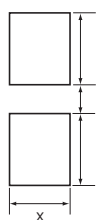


Surface Mount Type

Recommended Land Size (mm)



Size	X	Y	a			
φ3	1.6	2.2	0.8			
φ4	1.6	2.6	1.0			
φ5	1.6	3.0	1.4			
φ6.3	1.6	3.5	1.9			
φ8×5.4L, φ8×6.2L	2.5	4.0	2.1			
φ8 × 10L	2.5	3.5	3.0			
φ10	2.5	4.0	4.0			
Size	Welded terminal type			Perpendicularly mounted terminal type		
	X	Y	a	X	Y	a
φ12.5	4.0	7.5	7.0	2.0	7.3	3.0
φ16	6.0	8.5	9.5	2.0	7.9	5.3
φ18	6.0	9.5	10.5	2.0	8.9	5.3
φ20	6.0	9.5	12.5	2.4	8.7	7.8

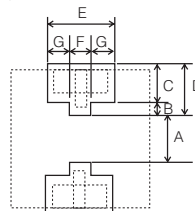
※ A chip product of φ12.5 or more in size and with a bent terminal shape indicates a product where the 11th digit of the product number code is "Q".

Vibration Resistance Type (CZ, CX, UE, BC series)

① φ6.3 to 10

Size	X	Y	a
φ6.3×10L	3.0	4.0	1.6
φ8×10L	4.3	5.3	2.0
φ10×10L	4.3	5.6	3.3

② φ12.5 to 20

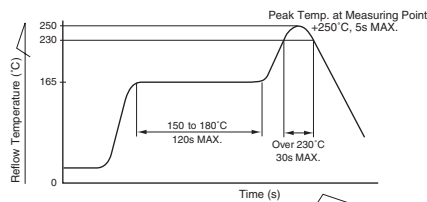


Size	A	B	C	D	E	F	G
φ12.5	3.0	2.3	5.0	7.3	7.0	2.0	2.5
φ16	5.3	2.9	5.0	7.9	7.0	2.0	2.5
φ18	5.3	3.1	5.8	8.9	11.0	2.0	4.5
φ20	7.8	2.9	5.8	8.7	12.0	2.4	4.8

Soldering by Reflow

Table-1

Chip Type Aluminum Electrolytic Capacitors



φ10 or Smaller

(ZS, ZP, ZT, WX*1, WR, WP*1, WT*1, WF, WG, UP, UT, UA, UL, CB, CW, CD*2, CL, CM, UD, UB*3, CJ, CZ, CX*2, UR, UX*3, UQ, UE*2, BC*2)

*1φ8×5.4L : Refer to the table-2

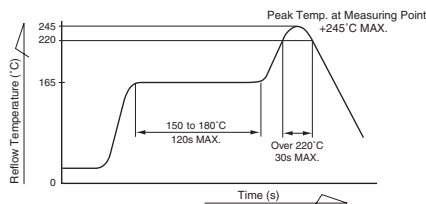
*2φ12.5 or greater : Refer to the table-4

*3160 to 400V : Refer to the table-3

- Pre - heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +250°C.
- The duration for over +230°C temperature at capacitor surface shall not exceed 30 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

Table-2

Chip Type Aluminum Electrolytic Capacitors

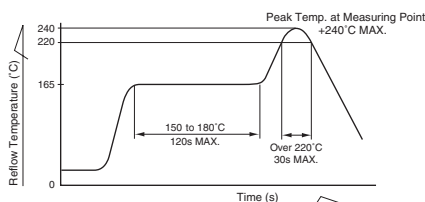


φ8×5.4L (WX, WP, WT)

- Pre - heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +245°C.
- The duration for over +220°C temperature at capacitor surface shall not exceed 30 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

Table-3

Chip Type Aluminum Electrolytic Capacitors

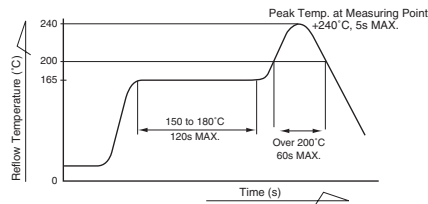


3L, 3.9L (ZD, ZR, ZE, ZG), UX(160 to 400V), UB(160 to 400V), LT, LH, LR, LV

- Pre - heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +240°C.
- The duration for over +220°C temperature at capacitor surface shall not exceed 30 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.(φ6.3 : 1 cycle only)
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

● Table-4
Chip Type Aluminum Electrolytic Capacitors

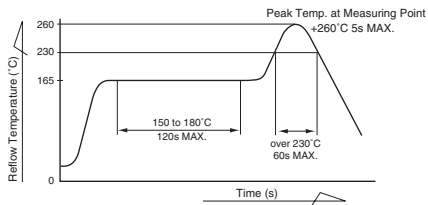
φ 12.5 or greater (CD, CX, UG, UJ, UN, UE, BC)



- Pre - heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor Top shall not exceed +240°C.
- The duration for over +200°C temperature at capacitor surface shall not exceed 60 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.
- Please contact us if capacitors are subject to the conditions other than the allowable range at reflow.

● Table-5
Chip Type Aluminum Electrolytic Capacitors

(For High Temp. Reflow) WJ, WZ, WD, WH, WS



- Pre - heating shall be done at +150°C to 180°C and for 120 seconds.
- The temperature at capacitor surface shall not exceed +260°C.
- The duration for over +230°C temperature at capacitor surface shall not exceed 60 seconds.
- The standard temperature profile differs by every reflow method.
- Reflow shall be done within 2 cycles. please make sure the parts have enough cooling down time between the first and second soldering process.
(φ8 × 6.2 and φ10 × 10 : 1 cycle only)
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

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